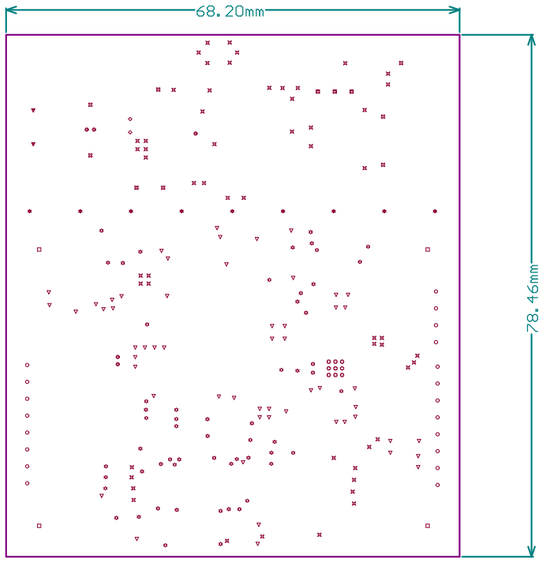
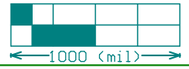
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 High Tg	23.00mil	4.8	
5	L2_GND-PLANE	Copper	1.40mil		
6	Dielectric2	FR-4 High Tg	12.00mil	4.8	
7	L3_PWR-PLANE	Copper	1.40mil		
8	Dielectric3	FR-4 High Tg	23.00mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
◎	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer
✪	9	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer
✖	56	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer
✡	58	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer
▽	56	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer
◇	2	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer
✱	9	32.00mil (0.813mm)	NPTH	Slot	Top Layer - Bottom Layer
▣	3	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer
⊠	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer
○	20	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer
▼	2	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer
□	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer
	232 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table
FOR 7.87MIL DRILL +0/-7.87MIL
FOR 8MIL DRILL +0/-8MIL
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL



DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
68.20MM X 78.46MM
Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.87 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.152mm (6MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
IMPEDENCE CONTROLLED BOARD:NO

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES VIA TENTING: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

Texas Instruments

PROJECT TITLE: TIDA-00300 Isolated PS and comm.Interface
DESIGNED FOR: Public Release
FILE NAME: TIDA-00300

ENGINEER: Sreenivasa		LAYOUT BY: Avinash N	
SCALE: 1.12		ALTIUM DESIGNER VERSION: 18.1.9.240	

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00300	REV: E3	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 00300		
PLOT NAME = Fabrication Drawing	GENERATED : 4/10/2019 11:57:52 AM	TEXAS INSTRUMENTS	

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